IN THE CLAIMS:

The following listing of the claims replaces all earlier listings and all earlier versions.

1. to 8. (Canceled)

9. (New) A light emitting diode, comprising at least one light emitting diode die, arranged on a light emitting diode printed circuit board by means of a die attach, the light emitting diode printed circuit board comprising at a bottom surface thereof rear side contacts,

wherein the rear side contacts at least partially overlap with contours of the light emitting diode die and are formed in such a way as to overlap with at least half of the bottom surface of the printed circuit board, and

wherein the printed circuit board comprises a plurality of through-contacts thermally and electrically connecting the rear side contacts to contact areas formed on an upper surface of the printed circuit board.

10. (New) A light emitting diode according to claim 9, wherein the light emitting diode printed circuit board is a metal core printed circuit board and wherein the light emitting diode die is located directly on the metal core.

11. (New) A light emitting diode according to claim 9, wherein the light emitting diode printed circuit board is a metal core printed circuit board and wherein a non-linear isolator material layer is arranged between contact areas and the metal core printed circuit board.

12. (New) A light emitting diode according to claim 9, 10, or 11, wherein the light emitting diode die is mounted face down on the light emitting diode printed circuit board.

13. (New) A light emitting diode light source having at least one light emitting diode according to claim 9 arranged on an additional board, wherein the additional board comprises on its upper surface contact areas which are soldered to the rear side contacts of the light emitting diode,

wherein a contact surface between the contact areas of the additional board and the rear side contacts of the light emitting diode is at least half of the surface of the printed circuit board of the light emitting diode, and

wherein the additional board comprises a plurality of through-contacts thermally and electrically connecting at least one of the contact areas to a solder area formed at the bottom of the additional board.

14. (New) A light emitting diode light source according to claim 13, wherein a cooling body is located at a rear side of the additional printed circuit board.

15. (New) A light emitting diode light source according to claim 13 or 14, wherein the through-contacts have a diameter of less than 100 μm.